



3rd Workshop on Robustness of IoT Devices Co-located at 2020 EOS/ESD Symposium

Sept 16-17, 2020

Peppermill Resort and Casino

Reno, NV, USA

CALL FOR PAPERS

3rd Workshop on Robustness of IoT Devices

Submission Deadline: March 1, 2020

About the Workshop on Robustness of IoT Devices

The third **Workshop on Robustness of IoT Devices** will establish an extended symposium-type event dedicated to the need of the growing world of IoT applications and their electrical robustness requirements. The IoT workshop is co-located at the 2020 EOS/ESD Symposium.

This workshop will facilitate evaluation of robustness risks in the diverse environments of IoT applications and a faster growth of innovative IC/module codesign approaches. IoT devices are now deployed in industrial, automotive, personal and commercial environments, each vector with its own constraints on the radio communications, power consumption and sensor features of IoT.

The topics to be addressed in this workshop include aspects of reliability and transients causing EOS. It covers the design and test of IP blocks, ICs and system modules and to enable sharing of commercially available techniques and offerings. Focus in the workshop is on the overlapping engineering domains bringing cross functional expertise together, fostering best-practice sharing and product innovation.

The workshop will include technical papers, invited seminars and panel discussions.

A program of technical presentations addressing the following fields of interest for IOT devices will be offered:

- **Device robustness requirements in industrial and automotive ecosystem**
 - o Characterization methods for robust/reliable IoT design including system- level testing
 - o Characterization of Safe Operating Area
 - o Mission profile and system lifetime assessment
- **Robust design approaches and validation with Rf and sensor integration**
 - o Case studies and related failure analysis
 - o IC/PCB/module co-design for reliability and robustness
 - o Design for a wide range of ambient conditions
- **IP and EDA landscape**
- **IP offerings and design environments for IoT**

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Submission Instructions

Authors are invited to submit a 250 word abstract contributing to these topics until March 1st, 2020 to info@esda.org. The abstract should indicate the field of interest and the key technical aspects of the proposed presentation. A presentation time of 20 minutes plus 5 minutes Q&A are offered. The final presentations are published in the electronic proceedings.

About the EOS/ESD Symposium

EOS/ESD Association, Inc. is sponsoring the 42nd Annual Symposium on Electrical Overstress (EOS) and Electrostatic Discharge (ESD) effects. The Symposium is dedicated to the understanding of issues related to electrostatic discharge and electrical transients / overstress, and the application of this knowledge to the solution of problems in consumer, industrial, and automotive applications, including electronic components and manufacturing, as well as in systems, subsystems, and equipment.

Management Committee

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